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Speech subject: Multi-scale multi-field simulation for chip design

Speech leader: *Yuzheng GUO, PhD., Vice Dean of School of Power and Mechanical Engineering, Wuhan University*

Speech Description/Objective:

Speech Outline:

Who Should Attend:

Introduction of Speaker:

Yuzheng GUO, Vice Dean of School of Power and Mechanical Engineering, Wuhan University, Professor of the Institute of Technological Sciences, School of Electrical Engineering and Automation, Zhongnan Hospital, and Dean of the Department of Energy Storage and New Energy. He received his bachelor's degree from the School of Physics of Peking University, his master's degree from the Department of Materials Science and Technology of the Georgia Institute of Technology, Ph.D. degree from the Department of Engineering, University of Cambridge (supervisor was Professor John Robertson, a fellow of the Royal Academy of Sciences and the Academy of Engineering).

He is committed to the research of micro-nano manufacturing, semiconductor devices and device co-design, energy storage materials and devices, etc. Except that, he has published more than 200 papers indexed by SCI, including Nature, Nature Communications, Science Advances and other international first-class journals, and his published papers have been cited more than 8,000 times. He has presided over a number of funds such as the Organization Department of the Central Committee of the CPC, Ministry of Science and Technology of PRC, National Natural Science Foundation of China, China Southern Power Grid, and the State Grid, with a total amount of more than 20 million yuan.